

IN THE SPECIFICATIONIN THE ABSTRACT

A semiconductor chip mounting component includes a support having a top surface, a bottom surface, a central portion, a peripheral portion surrounding the central portion, and a gap extending through the support structure between the top and bottom. The component includes a plurality of electrically conductive leads, each lead having a connection section extending across the gap, the connection section having a first end disposed on the support structure on one side of the gap, a second end secured to the support structure on an opposite side of the gap, and a frangible section between the first and second ends. The frangible section has a cross-sectional area that is smaller than a cross-sectional area of the connection section. The component also includes at least one elongated bus disposed on the peripheral portion of the support structure alongside the gap, whereby each lead extends across the gap and is connected to the bus. A semiconductor chip is disposed beneath the bottom surface of the support structure.